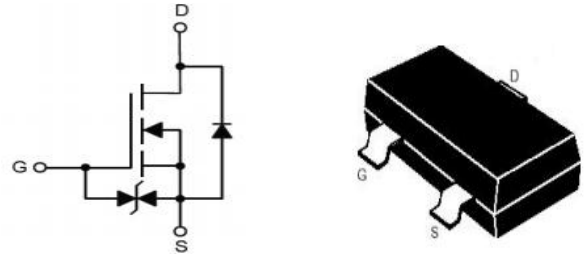


**SOT-323 30V N Channel ESD Protection 沟道带静电保护**  
**MOS Field Effect Transistor 场效应管**



■ **Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	30	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 20$	V
Drain Current (continuous)漏极电流-连续	$I_D$ (at $T_A = 25^\circ C$ )	100	mA
Drain Current (pulsed)漏极电流-脉冲	$I_{DM}$	0.1	A
Total Device Dissipation 总耗散功率	$P_D$ (at $T_A = 25^\circ C$ )	200	mW
ESD Protected Up to 人体模式静电保护范围	ESD(HBM)	2.0	kV
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	625	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	$^\circ C$

■ **Device Marking 产品字标**

2SK3018W=KN

■ Electrical Characteristics 电特性

( $T_A=25^{\circ}\text{C}$  unless otherwise noted 如无特殊说明, 温度为  $25^{\circ}\text{C}$ )

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压( $I_D=10\mu\text{A}, V_{GS}=0\text{V}$ )	$BV_{DSS}$	30	—	—	V
Gate Threshold Voltage 栅极开启电压( $I_D=100\mu\text{A}, V_{GS}=V_{DS}$ )	$V_{GS(th)}$	0.8	—	1.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流( $V_{GS}=0\text{V}, V_{DS}=30\text{V}$ )	$I_{DSS}$	—	—	0.2	$\mu\text{A}$
Gate Body Leakage 栅极漏电流( $V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$ )	$I_{GSS}$	—	—	$\pm 0.5$	$\mu\text{A}$
Static Drain-Source On-State Resistance 静态漏源导通电阻( $I_D=10\text{mA}, V_{GS}=4\text{V}$ ) ( $I_D=1\text{mA}, V_{GS}=2.5\text{V}$ )	$R_{DS(on)}$	—	—	8 13	$\Omega$
Diode Forward Voltage Drop 内附二极管正向压降( $I_{SD}=100\text{mA}, V_{GS}=0\text{V}$ )	$V_{SD}$	—	—	1.2	V
Input Capacitance 输入电容 ( $V_{GS}=0\text{V}, V_{DS}=5\text{V}, f=1\text{MHz}$ )	$C_{ISS}$	—	13	—	pF
Common Source Output Capacitance 共源输出电容( $V_{GS}=0\text{V}, V_{DS}=5\text{V}, f=1\text{MHz}$ )	$C_{OSS}$	—	9	—	pF
Reverse Transfer Capacitance 反馈电容( $V_{GS}=0\text{V}, V_{DS}=5\text{V}, f=1\text{MHz}$ )	$C_{RSS}$	—	4	—	pF
Total Gate Charge 栅极电荷密度 ( $V_{DS}=30\text{V}, I_D=100\text{mA}, V_{GS}=10\text{V}$ )	$Q_g$	—	1.6	—	nC
Gate Source Charge 栅源电荷密度 ( $V_{DS}=30\text{V}, I_D=100\text{mA}, V_{GS}=10\text{V}$ )	$Q_{gs}$	—	0.5	—	nC
Gate Drain Charge 栅漏电荷密度 ( $V_{DS}=30\text{V}, I_D=100\text{mA}, V_{GS}=10\text{V}$ )	$Q_{gd}$	—	0.3	—	nC
Turn-ON Delay Time 开启延迟时间 ( $V_{DS}=5\text{V}, I_D=10\text{mA}, R_{GEN}=10\Omega, V_{GS}=5\text{V}$ )	$t_{d(on)}$	—	15	—	ns
Turn-ON Rise Time 开启上升时间 ( $V_{DS}=5\text{V}, I_D=10\text{mA}, R_{GEN}=10\Omega, V_{GS}=5\text{V}$ )	$t_r$	—	35	—	ns
Turn-OFF Delay Time 关断延迟时间 ( $V_{DS}=5\text{V}, I_D=10\text{mA}, R_{GEN}=10\Omega, V_{GS}=5\text{V}$ )	$t_{d(off)}$	—	80	—	ns
Turn-OFF Fall Time 关断下降时间 ( $V_{DS}=5\text{V}, I_D=10\text{mA}, R_{GEN}=10\Omega, V_{GS}=5\text{V}$ )	$t_f$	—	80	—	ns

■ Typical Characteristic Curve 典型特性曲线

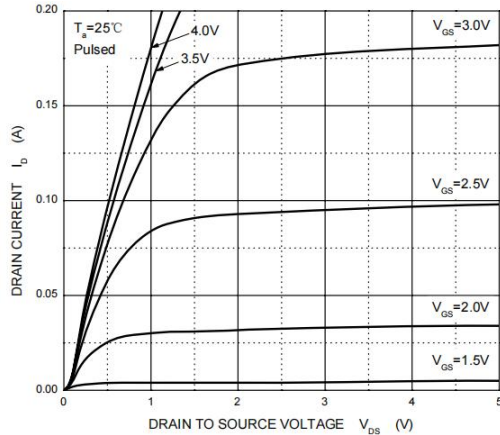


Figure 1: Output Characteristics

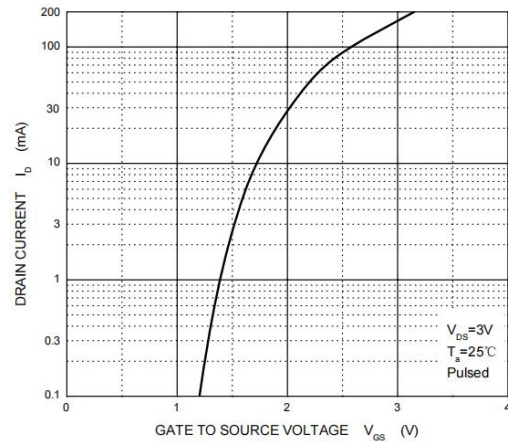


Figure 2: Transfer Characteristics

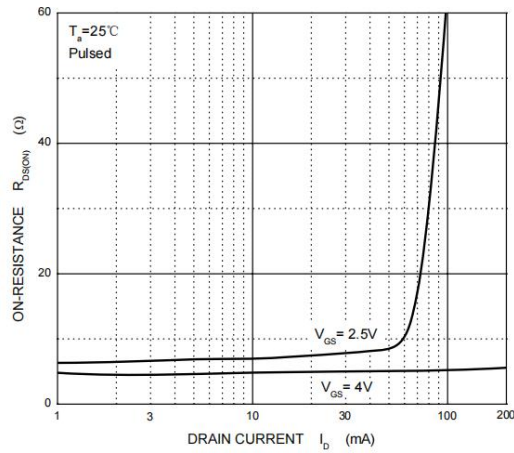


Figure 3: On-Resistance vs. Drain Current

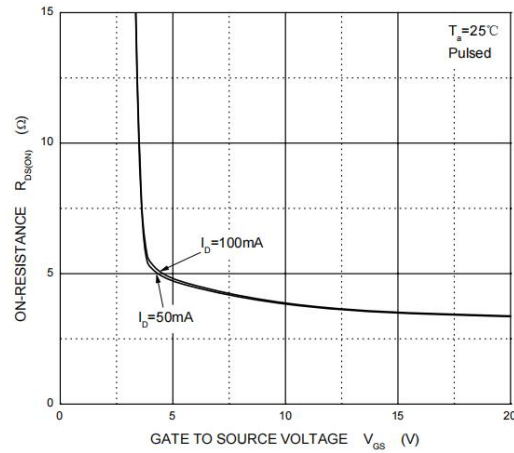


Figure 4: On-Resistance vs.  $V_{GS}$

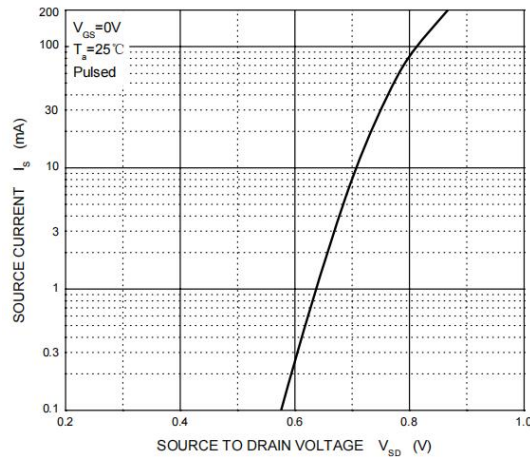
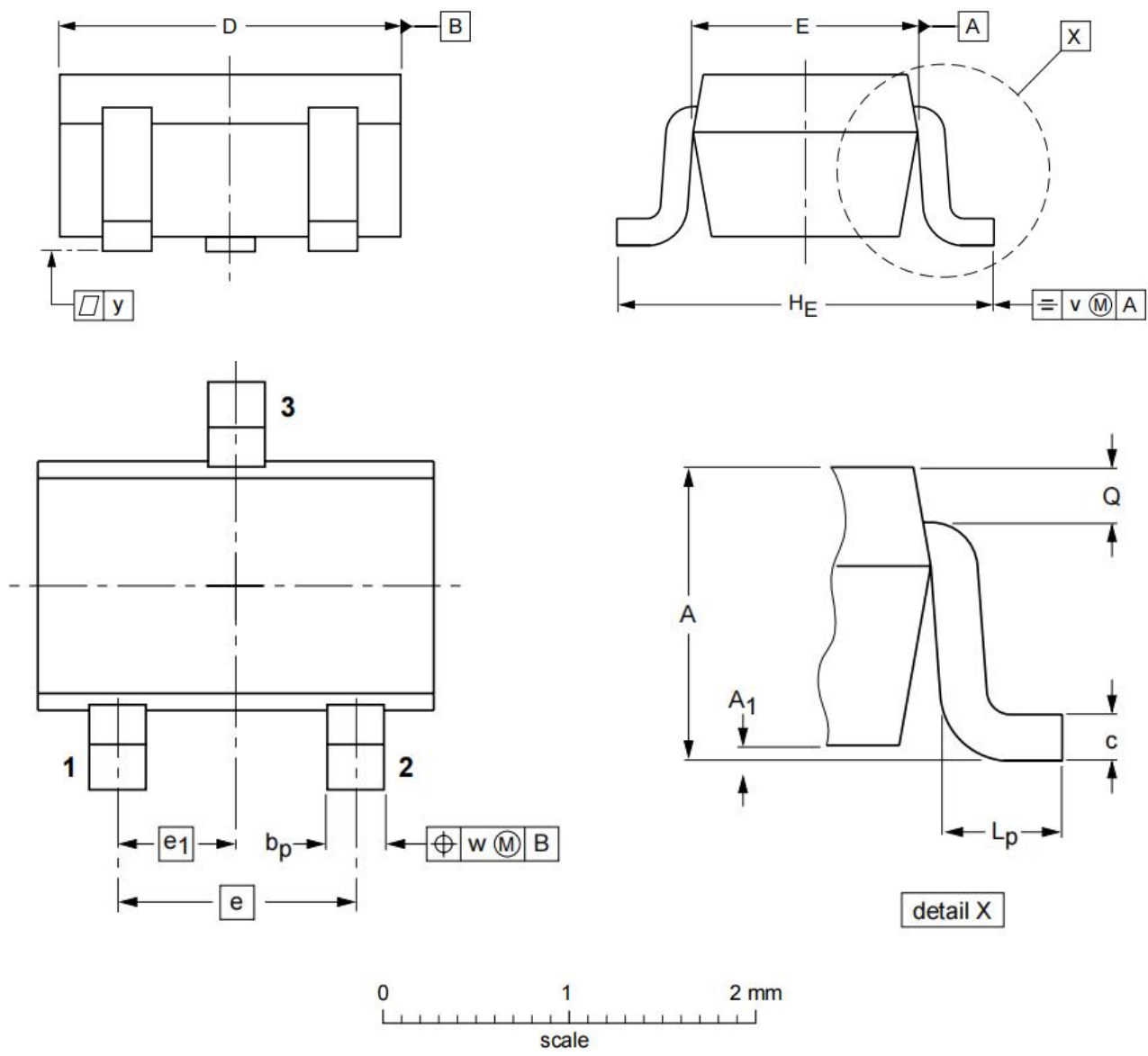


Figure 5: Body diode Characteristics

Dimension 外形封装尺寸



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2